

(19) 世界知的所有権機関
国際事務局



(43) 国際公開日
2001 年 7 月 5 日 (05.07.2001)

PCT

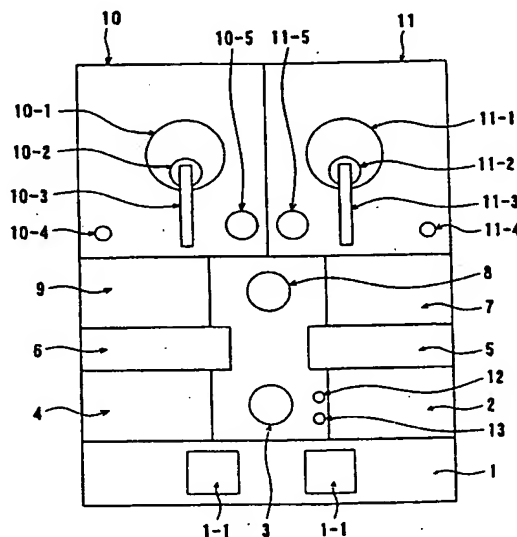
(10) 国際公開番号
WO 01/48800 A1

- (51) 国際特許分類: H01L 21/288 特願 2000/312695
2000 年 10 月 12 日 (12.10.2000) JP
- (21) 国際出願番号: PCT/JP00/09183
- (22) 国際出願日: 2000 年 12 月 25 日 (25.12.2000)
- (25) 国際出願の言語: 日本語
- (26) 国際公開の言語: 日本語
- (30) 優先権データ:
特願平 11/367754
1999 年 12 月 24 日 (24.12.1999) JP
特願 2000/65459 2000 年 3 月 9 日 (09.03.2000) JP
特願 2000/119861 2000 年 4 月 20 日 (20.04.2000) JP
特願 2000/121841 2000 年 4 月 21 日 (21.04.2000) JP
特願 2000/131879 2000 年 4 月 28 日 (28.04.2000) JP
特願 2000/132015 2000 年 5 月 1 日 (01.05.2000) JP
特願 2000/153754 2000 年 5 月 24 日 (24.05.2000) JP
特願 2000/165801 2000 年 6 月 2 日 (02.06.2000) JP
特願 2000/244355 2000 年 8 月 11 日 (11.08.2000) JP
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[続葉有]

(54) Title: SEMICONDUCTOR WAFER PROCESSING APPARATUS AND PROCESSING METHOD

(54) 発明の名称: 半導体基板処理装置及び処理方法



(57) Abstract: A semiconductor wafer processing apparatus and processing method, in which a circuit pattern groove and/or hole formed in a semiconductor wafer is filled with a metal plating film and the metal plating film is removed except for the portion in the groove/hole so as to fabricate circuit wiring. The semiconductor wafer processing apparatus comprises a load/unload unit (1) for loading/unloading a semiconductor wafer (W) in a dried state on which a circuit is fabricated, a film forming unit (2) for forming a metal plating film on the loaded semiconductor wafer, a bevel-etching unit (116) for etching the peripheral part of the semiconductor wafer, polishing units (10, 11) for polishing at least a part of the metal plating film on the semiconductor wafer, and robots (3, 8) for transferring the semiconductor wafer between the units.

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INTERNATIONAL SEARCH REPORT

International Publication No.

PCT/JP00/09183

A. CLASSIFICATION OF SUBJECT MATTER
Int.Cl.⁷ H01L21/288

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

Int.Cl.⁷ H01L21/288, C25D5/00-7/12, C25F1/00-7/02
B23H1/00-11/00, H01L21/68, H01L21/304Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched
Jitsuyo Shinan Koho 1926-1996 Toroku Jitsuyo Shinan Koho 1994-2001
Kokai Jitsuyo Shinan Koho 1971-2001 Jitsuyo Shinan Toroku Koho 1996-2001

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	EP, 903774, A (EBARA CORPORATION), 24 March, 1999 (24.03.99), Par. Nos. 0030-0057; Figs. 1-7 & JP, 11-154653, A Par. Nos. 0019-0043; Figs. 1-7	1-62
Y	JP, 7-107199, B (Shimada Rika Kogyo K.K.), 15 November, 1995 (15.11.95), example (Family: none)	1-4, 31, 33, 35, 36, 38, 41, 44, 49, 50-54, 62
Y	JP, 7-81197, B (NEC Corporation), 30 August, 1995 (30.08.95), Column 4, line 44 to Column 6, line 10 (Family: none)	1-4, 31, 33, 35, 36, 38, 41, 44, 49, 50-54, 62
PY	JP, 2000-328297, A (Dainippon Screen MFG. Co., Ltd.), 28 November, 2000 (28.11.00), Par. Nos. 0037-0053; Figs. 1, 2 (Family: none)	1-4, 31, 33, 35, 36, 38, 41, 44, 49
Y	JP, 11-87276, A (Ebara Corporation), 30 March, 1999 (30.03.99), Claim 4 (Family: none)	1-26, 36-45

☒ Further documents are listed in the continuation of Box C.☐ See patent family annex.

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Date of the actual completion of the international search
03 April, 2001 (03.04.01)Date of mailing of the international search report
17 April., 2001 (17.04.01)Name and mailing address of the ISA/
Japanese Patent Office

Authorized officer

Facsimile No.

Telephone No.

INTERNATIONAL SEARCH REPORT

International Publication No.

PCT/JP00/09183

C (Continuation). DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
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Y	JP, 9-53198, A (Denso Corporation), 25 February, 1997 (25.02.97), Par. No. 0013 (Family: none)	5-6
Y	JP, 11-269693, A (JAPAN ENERGY CORPORATION), 05 October, 1999 (05.10.99), Claims (Family: none)	7-13
Y	EP, 761387, A (EBARA CORPORATION), 12 March, 1997 (12.03.97), page 5, line 2 to page 6, line 7 & JP, 9-117857, A, Par. Nos. 0022-0025	16-18
Y	JP, 11-198033, A (Canon Inc.), 27 July, 1999 (27.07.99), Claims & US, 6142855, A	29, 30, 55-61
Y	JP, 10-335288, A (Sony Corporation), 18 December, 1998 (18.12.98), Claims (Family: none)	29, 30, 55-61
Y	JP, 10-209091, A (Nikon Corporation), 07 August, 1998 (07.08.98), Claims (Family: none)	29, 30, 55-61
Y	JP, 9-36072, A (Toshiba Corporation), 07 February, 1997 (07.02.97), Claims (Family: none)	29, 30, 55-61
Y	JP, 8-316179, A (Sony Corporation), 29 November, 1996 (29.11.96), Claims (Family: none)	29, 30, 55-61
Y	JP, 8-240413, A (Toshiba Corporation), 17 September, 1996 (17.09.96), Claims (Family: none)	29, 30, 55-61
Y	JP, 55-85692, A (Hitachi, Ltd.), 27 June, 1980 (27.06.80), Claims; Fig. 6 (Family: none)	32, 37, 40, 43
Y	US, 5853559, A (Mitsubishi Denki Kabushiki Kaisha), 29 December, 1998 (29.12.98), Column 3, line 61 to Column 4, line 37; Fig.1 & JP, 10-226896, A, Par. No. 0010; Fig.1	34, 39, 40, 42, 43, 46-48, 50-54, 62
Y	JP, 6-169003, A (Toshiba Corporation), 14 June, 1994 (14.06.94), Par. No. 0018 (Family: none)	55-61